114, 160, as described in connection with Figure 2, can be eliminated. Plated through hole 124 includes a conductive pad 162 formed on a first surface 120 of substrate 114. It will be appreciated that other electrically conductive circuitry 121 may be formed on surface 120.

IN THE CLAIMS:

Please cancel claim 9.

Please amend the claims as follows:

8. (Amended) The printed circuit board as recited in claim 2, further comprising at least one clearance between said electrically conductive circuitry and said plated through hole filled with said dielectric material.

10. (Amended) The electronic device package as recited in claim 48 further comprising at least one power plane.

11. (Amended) The electronic device package as recited in claim 48 further including a second substrate comprising impregnated glass fibers, a power plane and a second non-conductive layer positioned between said second substrate and said power plane.

12. (Amended) The electronic device package as recited in claim 10 further comprising at least one plated through hole extending through said substrate and said non-conductive layer.

13. (Amended) The electronic device package as recited in claim 12 wherein said power plane is spaced from said through hole and said electronic device package further includes a non-conductive layer comprising a dielectric material free of continuous glass fibers in the space between said power plane and said through hole to prevent a short there between.

14. (Amended) The electronic device package as recited in claim 12 wherein said non-conductive layer is positioned between said through hole and said electrically conductive circuit.

15. (Amended) The electronic device package as recited in claim 48 further comprising at least one clearance filled with said dielectric material.

A3 cancelled

16. (Amended) The electronic device package as recited in claim 48 further including an electronic device electrically coupled to said electrically conductive circuit.

17. (Amended) The electronic device package as recited in claim 48 wherein said electrically conductive circuit includes a plurality of solder pads.

19. (Amended) The electronic device package as recited in claim 48 wherein said dielectric material comprises a photoimageable dielectric material.

A4

20. (Amended) The electronic device package as recited in claim 48 wherein said dielectric material comprises polyimide.

21. (Amended) The electronic device package as recited in claim 48 wherein said dielectric material comprises Kevlar-based paper impregnated with epoxy resin.

22. (Amended) The electronic device package as recited in claim 48 wherein said dielectric material comprises resin-coated copper foil.

23. (Amended) The electronic package device as recited in claim 48 wherein said substrate layer is prepreg comprising glass fabric impregnated with epoxy resin.

A5

32. (Amended) The electronic device package as recited in claim 31 further including additional non-conductive layers positioned between said substrates and said power planes.

A6

35. (Amended) The electronic device package as recited in claim 32 further comprising at least one clearance between said electrically